



### Discription

The HPSP36 protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events. Excellent clamping capability, low leakage, low capacitance, and fast response time provide best in class protection on designs that are exposed to ESD. It gives designer the flexibility to protect one unidirectional line in applications where arrays are not practical.



SOD-323

### Features

- ★ Unidirectional ESD protection of one line
- ★ Reverse stand-off voltage: 36.0V Max
- ★ Low leakage current: uA Level
- ★ Response time is typically < 1 us
- ★ Low clamping voltage:  $V_C = 70\text{ V} @ I_{PP} = 4\text{ A}$
- ★ ESD Protection: 30kV(air)/ 30kV(contact)  
( IEC61000-4-2)
- ★ RoHS compliant



Circuit Diagram

### Ordering information

Product ID	Pack	Qty(PCS)
HPSP36	SOD-323	3000

### Absolute Ratings(Tamb = 25°C)

Symbol	Parameter	Value	Units
$P_{PP}$	Peak Pulse Power ( $t_p = 8/20 \mu\text{ s}$ )	350	W
$T_L$	Maximum lead temperature for soldering during 10s	260	°C
$T_{stg}$	Storage Temperature Range	-55 to +155	°C
$T_{op}$	Operating Temperature Range	-40 to +125	°C
$T_j$	Maximum junction temperature	150	°C
	IEC61000-4-2 (ESD)	air discharge contact discharge	$\pm 30$ $\pm 30$ KV



**Electrical Characteristics** Ratings at 25°C ambient temperature unless otherwise specified. VF = 0.9V at IF = 10mA

$V_{RWM}$ (V)	$I_R$ ( $\mu$ A) @ $V_{RWM}$	$V_{BR}$ (V)@ $I_T$ (Note 1)	$I_T$	$V_C$ (V) @ $I_{PP}=1$ A*	$V_C$ (V) @ Max $I_{PP}$ *	$I_{PP}$ (A)*	$P_{PK}$ (W)*	C (pF)
Max	Max	Min	mA	Typ	Max	Max	Max	Max
36	1.0	38	1	55	70	4	350	50

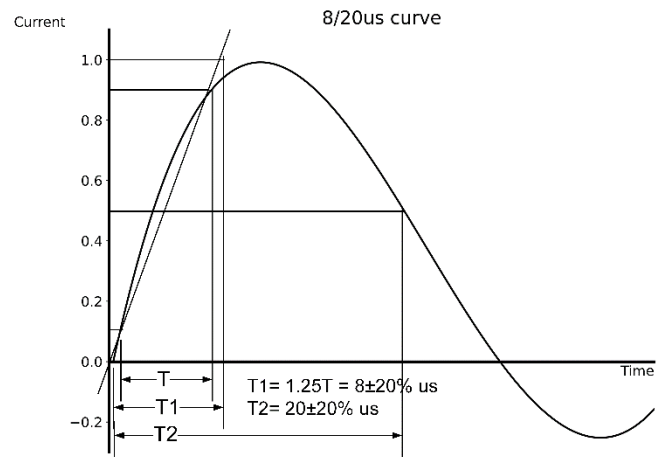
\*Surge current waveform per Figure 1.

- $V_{BR}$  is measured with a pluse test current  $I_T$  at an ambient temperature of 25°C.

**Typical Characteristics** ( $T_A=25^\circ\text{C}$  unless otherwise Specified)



Non-repetitive peak pulse power vs. pulse time





## Outline And Dimensions

Notes:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.



DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.8	0.9	1	0.031	0.035	0.04
A1	0	0.05	0.1	0	0.002	0.004
A3	0.15REF			0.006REF		
b	0.25	0.32	0.4	0.01	0.012	0.016
C	0.089	0.12	0.177	0.003	0.005	0.007
D	1.6	1.7	1.8	0.062	0.066	0.07
E	1.15	1.25	1.35	0.045	0.049	0.053
L	0.08			0.003		
HE	2.3	2.5	2.7	0.09	0.098	0.105

## Soldering Footprint





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